

Electronic Acknowledgement Receipt

EFS ID:	1250086
Application Number:	10717122
Confirmation Number:	7303
Title of Invention:	Dielectric barrier layer for a copper metallization layer having a varying silicon concentration along its thickness
First Named Inventor:	Larry Zhao
Customer Number:	23720
Filer:	J. Mike Amerson/Mary Paul
Filer Authorized By:	J. Mike Amerson
Attorney Docket Number:	2000.106900
Receipt Date:	12-OCT-2006
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Application Type:	Utility
International Application Number:	

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Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		Response_to_Office_Action_Dated_7_12_06.pdf	99468	yes	6

	Multipart Description		
	Doc Desc	Start	End
	Amendment - After Non-Final Rejection	1	1
	Applicant Arguments/Remarks Made in an Amendment	2	6

Warnings:

Information:

Total Files Size (in bytes):

98468

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.